

Electronic Patent Application Fee Transmittal

Application Number:	10719218			
Filing Date:	20-Nov-2003			
Title of Invention:	Structure, material, and design for assembling a low-K Si die to achieve an industrial grade reliability wire bonding package			
First Named Inventor/Applicant Name:	Wen-Chou Vincent Wang			
Filer:	James W. Rose/Laura Dean			
Attorney Docket Number:	ALTRP100/A1198			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790